

What I claim is:

1. A method for electrofilling a metal or alloy inside at least one opening located in a front surface of a substrate, said front surface of the substrate comprises the at least one opening and a top field surrounding the at least one opening,
5 said at least one opening comprises a bottom and sidewalls surfaces wherein at least the bottom surface comprises an exposed metallic surface, said method includes steps of:
immersing the substrate in an activation (or wetting) solution;
applying ultrasonic or megasonic vibrations to the substrate and to the activation (or wetting) solution;
10 applying high pressure electrolyte jets to the substrate, said electrolyte comprises metallic ions of said metal or alloy; and
applying an electroplating current to the substrate to electroplate said metal or alloy inside the at least one opening.
2. The method of claim 1 wherein the electrolyte further comprises at
15 least one inhibitor additive.